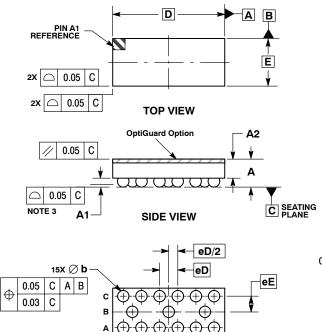




WLCSP15, 2.47x1.05 CASE 567BR-01 **ISSUE O**

DATE 26 JUL 2010

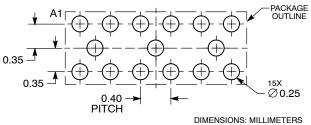


BOTTOM VIEW

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.54	0.69	
A1	0.17	0.24	
A2	0.42 REF		
b	0.24	0.29	
D	2.47 BSC		
E	1.05 BSC		
eD	0.400 BSC		
еE	0.347 BSC		

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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